PLASTIC PACKAGING FOR A SURFACE MOUNTED INTEGRATED CIRCUIT

ABSTRACT OF THE DISCLOSURE

After completing this macro, return to each appropriate section and type the information provided by the attorney. In accordance with the invention, integrated circuit dies may be packaged in a plastic package employing an area area array technology such as a conductive ball grid array, column grid array or pin grid array. One aspect of the invention is an integrated circuit package(10) which includes an electronic circuit enclosed by a plastic body (12, 14). The molded plastic body has a first major surface opposing a second major surface. The first major surface of integrated circuit (10) has a plurality of openings therein. One of a plurality of conductive pads (18) is adjacent to each one of the openings and is electrically connected to the electronic circuit. Each of a plurality of conductors (20) is electrically connected to one of the pads (18) and protrudes from one of the openings (22).

Figure 1 & 3

This Sheet Has Been Replaced

